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**FEATURES** 

## **Advanced Power MOSFET**

# IRFM120A

 $BV_{DSS} = 100 V$ 

 $R_{DS(on)} = 0.2 \Omega$ 

## IEEE802.3af Compatible

- □ Avalanche Rugged Technology
- □ Rugged Gate Oxide Technology
- Lower Input Capacitance
- □ Improved Gate Charge
- □ Extended Safe Operating Area
- $\square$  Lower Leakage Current : 10  $\mu A$  (Max.) @ V\_{DS} = 100V
- $\Box$  Lower R<sub>DS(ON)</sub> : 0.155  $\Omega$  (Typ.)

**Absolute Maximum Ratings** 



#### 1. Gate 2. Dra

Symbol	Characteristic	Value	Units	
V <sub>DSS</sub>	Drain-to-Source Voltage	100	V	
	Continuous Drain Current (T <sub>A</sub> =25°C)	2.3		
Ι <sub>D</sub>	Continuous Drain Current (T <sub>A</sub> =70°C)	1.84	A	
I <sub>DM</sub>	Drain Current-Pulsed ①	18	А	
V <sub>GS</sub>	Gate-to-Source Voltage	±20	V	
E <sub>AS</sub>	Single Pulsed Avalanche Energy (2)	123	mJ	
I <sub>AR</sub>	Avalanche Current (1)	2.3	А	
E <sub>AR</sub>	Repetitive Avalanche Energy (1)	0.24	mJ	
dv/dt	Peak Diode Recovery dv/dt 3	6.5	V/ns	
PD	Total Power Dissipation $(T_A=25^{\circ}C)$ *	2.4	W	
• 0	Linear Derating Factor *	0.019	W/℃	
	Operating Junction and			
$T_J$ , $T_STG$	Storage Temperature Range	- 55 to +150	°0	
	Maximum Lead Temp. for Soldering	000	C	
TL	Purposes, 1/8" from case for 5-seconds	300		

#### **Thermal Resistance**

Symbol	Characteristic	Тур.	Max.	Units
$R_{ ext{ heta}JA}$	Junction-to-Ambient *	-	52	°C/W

\* When mounted on the minimum pad size recommended (PCB Mount).

Symbol	Characteristic	Min.	Тур.	Max.	Units	Test Condition	
$BV_{DSS}$	Drain-Source Breakdown Voltage	100			V	V <sub>GS</sub> =0V,I <sub>D</sub> =250µA	
$\Delta \text{BV} / \Delta \text{T}_{\text{J}}$	Breakdown Voltage Temp. Coeff.		0.12		V/℃	I <sub>D</sub> =250μA <b>See Fig 7</b>	
V <sub>GS(th)</sub>	Gate Threshold Voltage	2.0		4.0	V	V <sub>DS</sub> =5V,I <sub>D</sub> =250µA	
	Gate-Source Leakage, Forward			100	nA	V <sub>GS</sub> =20V	
I <sub>GSS</sub>	Gate-Source Leakage, Reverse			-100	ΠA	V <sub>GS</sub> =-20V	
				1		V <sub>DS</sub> =30V (6)	
I <sub>DSS</sub>	Drain-to-Source Leakage Current			10	μA	V <sub>DS</sub> =100V	
				100		V <sub>DS</sub> =80V,T <sub>A</sub> =125℃	
R <sub>DS(on)</sub>	Static Drain-Source On-State Resistance			0.2	Ω	V <sub>GS</sub> =10V,I <sub>D</sub> =1.15A ④	
9 <sub>fs</sub>	Forward Transconductance		3.12		S	V <sub>DS</sub> =40V,I <sub>D</sub> =1.15A ④	
C <sub>iss</sub>	Input Capacitance		370	480			
C <sub>oss</sub>	Output Capacitance		95	110	рF	$V_{GS}=0V, V_{DS}=25V, f=1MHz$	
C <sub>rss</sub>	Reverse Transfer Capacitance		38	45	-	See Fig 5	
t <sub>d(on)</sub>	Turn-On Delay Time		14	40			
t <sub>r</sub>	Rise Time		14	40		V <sub>DD</sub> =50V,I <sub>D</sub> =9.2A,	
t <sub>d(off)</sub>	Turn-Off Delay Time		36	90	ns	R <sub>G</sub> =18Ω	
t <sub>f</sub>	Fall Time		28	70		<b>See Fig 13</b> ④ 5	
Q <sub>q</sub>	Total Gate Charge		16	22		V <sub>DS</sub> =80V,V <sub>GS</sub> =10V,	
Q <sub>gs</sub>	Gate-Source Charge		2.7		nC	I <sub>D</sub> =9.2A	
Q <sub>gd</sub>	Gate-Drain("Miller") Charge		7.8			<b>See Fig 6 &amp; Fig 12</b> ④ 5	

Electrical Characteristics (T <sub>A</sub> =25°C	unless	otherwise	specified)
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### Source-Drain Diode Ratings and Characteristics

Symbol	Characteristic	Min.	Тур.	Max.	Units	Test Condition
ا <sub>s</sub>	Continuous Source Current			2.3	^	Integral reverse pn-diode
I <sub>SM</sub>	Pulsed-Source Current ①			18	A	in the MOSFET
V <sub>SD</sub>	Diode Forward Voltage ④			1.5	V	T <sub>J</sub> =25 ℃,I <sub>S</sub> =2.3A,V <sub>GS</sub> =0V
t <sub>rr</sub>	Reverse Recovery Time		98		ns	T <sub>J</sub> =25℃,I <sub>F</sub> =9.2A
Q <sub>rr</sub>	Reverse Recovery Charge		0.34		μC	di <sub>F</sub> /dt=100A/µs ④

#### Notes;

① Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature

② L=35mH,  $I_{AS}$ =2.3A,  $V_{DD}$ =25V,  $R_{G}$ =27Ω, Starting  $T_{J}$ =25°C

3 I\_{SD}{\leq}9.2A, di/dt{\leq}300A/\mu s, V\_{DD}{\leq}BV\_{DSS} , Starting T\_J=25  $\degree$ C

④ Pulse Test : Pulse Width =  $250\mu s$ , Duty Cycle  $\leq 2\%$ 

(5) Essentially Independent of Operating Temperature

(6) Adjusted for Cisco

# IRFM120A









Fig 2. Transfer Characteristics



Fig 4. Source-Drain Diode Forward Voltage









#### Fig 12. Gate Charge Test Circuit & Waveform







Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms





## IRFM120A



#### Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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